

CLAIMS

What is claimed is:

1. An on-chip capacitor comprising:

a first electrode formed during a first deposition of a first metal layer of a

5 multi-level semiconductor device;

a substantially thin dielectric layer configured to be deposited over said first

electrode; and

a second electrode formed during a second deposition of a second metal layer

of said multi-level deposition device, wherein said second electrode is formed over said

10 substantially thin dielectric layer, wherein said on-chip capacitor is formed in a crossover area
of said first metal layer and said second metal layer of said multi-level semiconductor device.

2. The on-chip capacitor according to claim 1, wherein an angle of

intersection between said first metal layer and said second metal layer is between zero and

15 ninety degrees.

3. The on-chip capacitor according to claim 1, wherein said first electrode

and said second electrode are configured to be substantially parallel.

20 4. The on-chip capacitor according to claim 3, wherein said first electrode

and said second electrode are further configured to be overlapping.

5. The on-chip capacitor according to claim 1, wherein said first electrode and said second electrode are configured as a rectangular planar structure.

6. The on-chip capacitor according to claim 5, wherein said first electrode 5 and said second electrode are substantially parallel and overlapping.

7. The on-chip capacitor according to claim 1, wherein said substantially thin dielectric material comprises a composite of materials.

10 8. The on-chip capacitor according to claim 7, wherein said composite of materials includes PZT and platinum.

9. The on-chip bypass capacitor according to claim 1, wherein a dielectric constant of said substantially thin dielectric material layer is substantially high.

15 10. The on-chip bypass capacitor according to claim 9, wherein said substantially thin dielectric material layer includes silicon nitride.

11. The on-chip bypass capacitor according to claim 11, wherein said 20 thickness of said substantially thin dielectric material layer is between 50 to 100 angstroms.